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NCE N-Channel Enhancement Mode Power MOSFET

Description

The NCE0140K uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

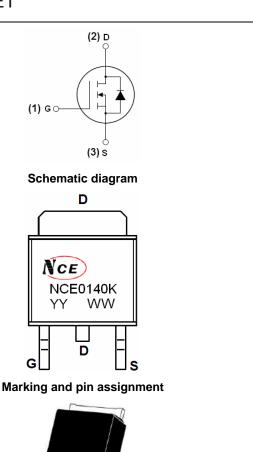
- V_{DS} = 100V, I_{D} =40A $R_{DS(ON)}$ < 17mΩ @ V_{GS} =10V (Typ:14mΩ)
- Special process technology for high ESD capability
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED!

100% ΔVds TESTED!



TO-252-2L top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
0140K	NCE0140K	TO-252-2L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous	I _D	40	А
Drain Current-Continuous(T _C =100 °C)	I _D (100℃)	28	Α
Pulsed Drain Current	I _{DM}	160	Α
Maximum Power Dissipation	P _D	140	W
Derating factor	-	0.94	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	520	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 175	$^{\circ}$ C

NCE0140K

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{ heta JC}$	1.07	°C/W	
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Electrical Characteristics (T_C=25 °C unless otherwise noted)

Parameter	Symbol	Symbol Condition		Тур	Max	Unit
Off Characteristics	·					
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	•		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS}$, $I_{D}=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =28A	-	14	17	mΩ
Forward Transconductance	g FS	V _{DS} =25V,I _D =28A	32	-	-	S
Dynamic Characteristics (Note4)	·					
Input Capacitance	C _{lss}	\/ -20\/\/ -0\/	-	3400	-	PF
Output Capacitance	Coss	V_{DS} =30V, V_{GS} =0V, F=1.0MHz	-	290	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.UIVIDZ	-	221	-	PF
Switching Characteristics (Note 4)	·					
Turn-on Delay Time	t _{d(on)}		-	15	-	nS
Turn-on Rise Time	t _r	VDD=30V,ID=2A,RL=15Ω,	-	11	-	nS
Turn-Off Delay Time	t _{d(off)}	RG=2.5Ω,VGS=10V	-	52	-	nS
Turn-Off Fall Time	t _f		-	13	-	nS
Total Gate Charge	Qg		-	94	-	nC
Gate-Source Charge	Q _{gs}	ID=30A,VDD=30V,VGS=10V	-	16	-	nC
Gate-Drain Charge	Q_{gd}		-	24	-	nC
Drain-Source Diode Characteristics	·					
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =28A	-	0.85	1.2	V
Diode Forward Current (Note 2)	Is		-	-	40	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 28A	-	33		nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs ^(Note3)	-	54		nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

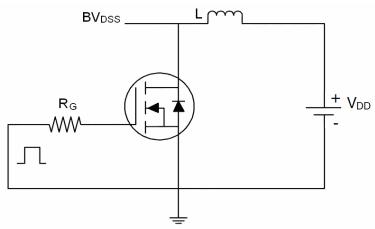
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition: Tj=25 $^{\circ}\text{C}$,VDD=50V,VG=10V,L=0.5mH,Rg=25 Ω

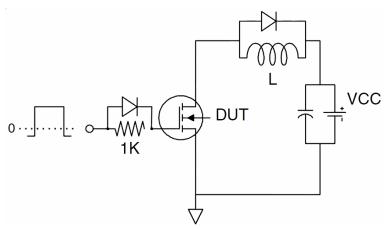


Test Circuit

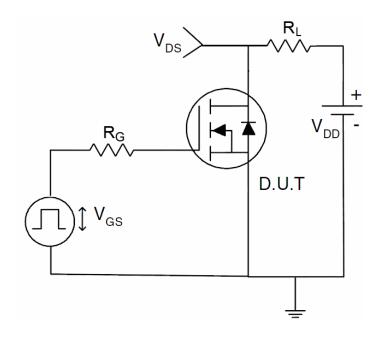
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



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Typical Electrical and Thermal Characteristics (Curves)

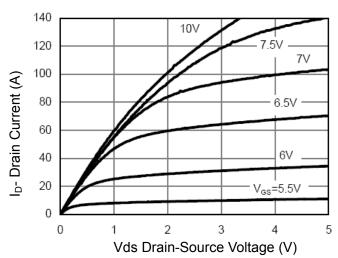


Figure 1 Output Characteristics

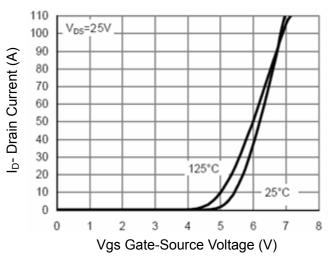


Figure 2 Transfer Characteristics

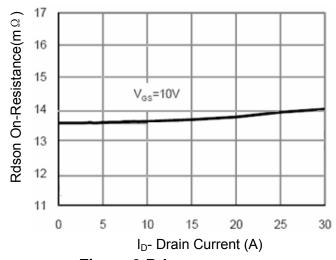


Figure 3 Rdson- Drain Current

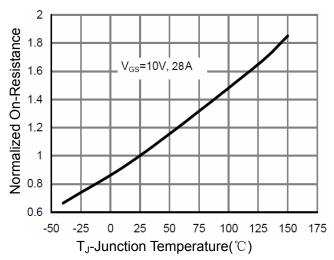


Figure 4 Rdson-JunctionTemperature

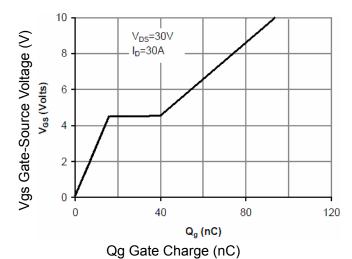


Figure 5 Gate Charge

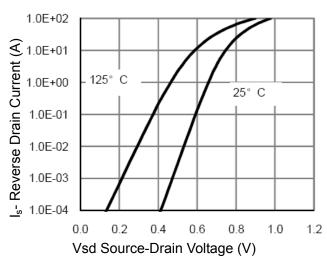


Figure 6 Source- Drain Diode Forward



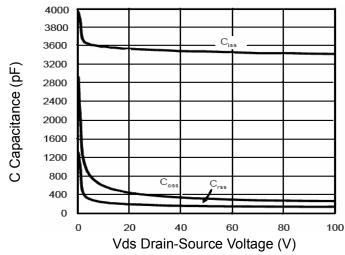


Figure 7 Capacitance vs Vds

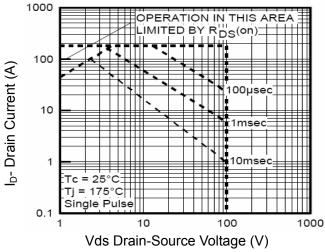


Figure 8 Safe Operation Area

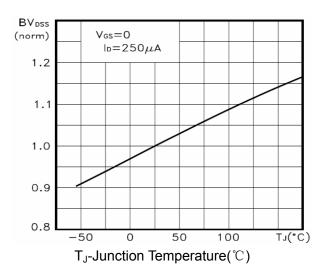


Figure 9 BV_{DSS} vs Junction Temperature

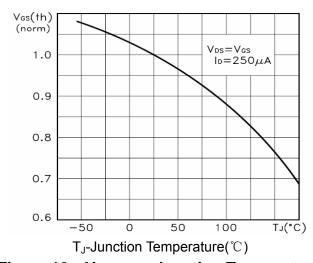


Figure 10 V_{GS(th)} vs Junction Temperature

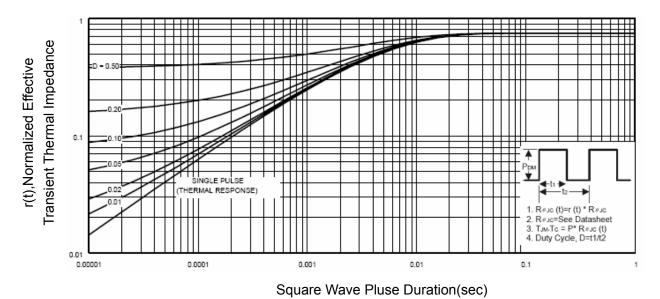
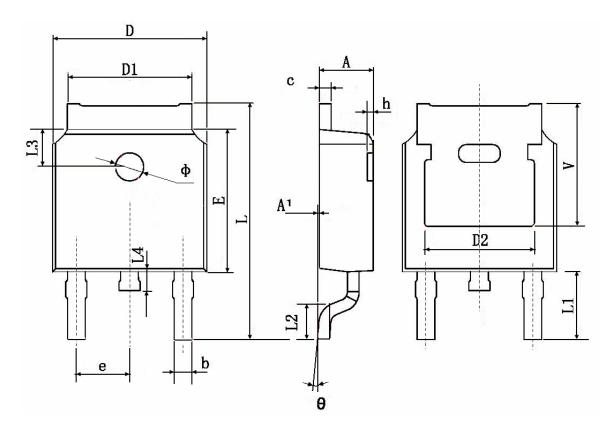


Figure 11 Normalized Maximum Transient Thermal Impedance

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TO-252 Package Information



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	TYP.	0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063	TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



http://www.ncepower.com

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